

# GUFB30H-20E

## FAST SINTERED GLASS JUNCTION RECTIFIER

VOLTAGE: 2000V

CURRENT: 2.0A

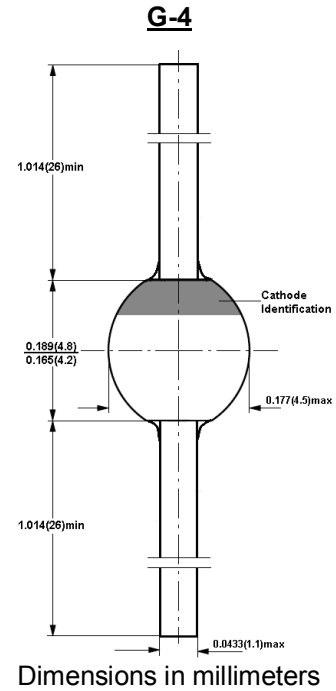


### FEATURE

High temperature metallurgically bonded construction  
Sintered glass cavity free junction  
Capability of meeting environmental standard of MIL-S-19500  
High temperature soldering guaranteed  
350→C /10sec/0.375"lead length at 5 lbs tension

### MECHANICAL DATA

Terminal: Plated axial leads solderable per J-STD-002  
Case: G-4 sintered glass case  
Polarity: color band denotes cathode  
Mounting position: any



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25→C, unless otherwise stated)

	Symbol	GUFB30H-20E	units
Maximum Recurrent Peak Reverse Voltage	V <sub>rrm</sub>	2000	V
Maximum RMS Voltage	V <sub>rms</sub>	1400	V
Maximum DC blocking Voltage	V <sub>dc</sub>	2000	V
Maximum Average Forward Rectified Current 3/8"lead length at T <sub>L</sub> =40°C	I <sub>f(av)</sub>	2.0	A
Peak Forward Surge Current 8.3ms single Half sine-wave superimposed on rated load	I <sub>fsm</sub>	50	A
Maximum Instantaneous Forward Voltage at 2.0A	V <sub>f</sub>	3.5	V
Maximum DC Reverse Current Ta =25°C	I <sub>r</sub>	2.0	→A
at rated DC blocking voltage Ta =150°C		100	
Maximum Reverse Recovery Time (Note 1)	T <sub>rr</sub>	150	nS
Typical Junction Capacitance (Note 2)	C <sub>j</sub>	35.0	pF
Typical Thermal Resistance (Note 3)	R <sub>th(jl)</sub>	18.0	°C/W
Storage and Operating Junction Temperature	T <sub>stg</sub> , T <sub>j</sub>	-65 to +175	°C

Note:

1. Reverse Recovery Condition I<sub>f</sub>=0.5A, I<sub>r</sub>=1.0A, I<sub>rr</sub>=0.25A
2. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
3. Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

## RATINGS AND CHARACTERISTIC CURVES GUFB30H-20E

